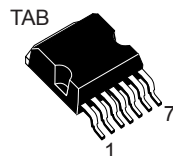
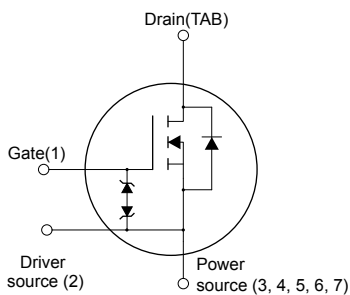


## Automotive-grade N-channel 650 V, 102 mΩ typ., 28 A MDmesh DM6 Power MOSFET in an H<sup>2</sup>PAK-7 package



**H<sup>2</sup>PAK-7**


N-chG1DS2PS34567DTABZ



### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STH30N65DM6-7AG	650 V	115 mΩ	28 A

- AEC-Q101 qualified 
- Fast-recovery body diode
- Lower R<sub>DS(on)</sub> per area vs previous generation
- Low gate charge, input capacitance and resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

### Applications

- Switching applications

### Description

This high-voltage N-channel Power MOSFET is part of the MDmesh DM6 fast-recovery diode series. Compared with the previous MDmesh fast generation, DM6 combines very low recovery charge (Q<sub>rr</sub>), recovery time (t<sub>rr</sub>) and excellent improvement in R<sub>DS(on)</sub> per area with one of the most effective switching behaviors available in the market for the most demanding high-efficiency bridge topologies and ZVS phase-shift converters.

#### Product status link

[STH30N65DM6-7AG](#)

#### Product summary

<b>Order code</b>	STH30N65DM6-7AG
<b>Marking</b>	30N65DM6
<b>Package</b>	H <sup>2</sup> PAK-7
<b>Packing</b>	Tape and reel

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	28	A
$I_D$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	18	A
$I_{DM}^{(1)}$	Drain current (pulsed)	112	A
$P_{TOT}$	Total power dissipation at $T_C = 25\text{ }^\circ\text{C}$	223	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	100	V/ns
$di/dt^{(2)}$	Peak diode recovery current slope	1000	A/ $\mu\text{s}$
$dv/dt^{(3)}$	MOSFET $dv/dt$ ruggedness	100	V/ns
$T_J$	Operating junction temperature range	-55 to 150	$^\circ\text{C}$
$T_{stg}$	Storage temperature range		$^\circ\text{C}$

1. Pulse width limited by safe operating area.
2.  $I_{SD} \leq 28\text{ A}$ ,  $V_{DS}(\text{peak}) < V_{(BR)DSS}$ ,  $V_{DD} = 400\text{ V}$ .
3.  $V_{DS} \leq 520\text{ V}$ .

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance, junction-to-case	0.56	$^\circ\text{C/W}$
$R_{thJB}^{(1)}$	Thermal resistance, junction-to-board	30	$^\circ\text{C/W}$

1. When mounted on FR-4 board of 1 inch<sup>2</sup>, 2 oz Cu.

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or non-repetitive (pulse width limited by $T_J$ max)	4	A
$E_{AS}$	Single pulse avalanche energy (starting $T_J = 25\text{ }^\circ\text{C}$ , $I_D = I_{AR}$ , $V_{DD} = 100\text{ V}$ )	600	mJ

## 2 Electrical characteristics

$T_C = 25\text{ °C}$  unless otherwise specified.

**Table 4. On/off-state**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$ , $I_D = 1\text{ mA}$	650			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$ , $V_{DS} = 650\text{ V}$			5	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$ , $V_{DS} = 650\text{ V}$ , $T_C = 125\text{ °C}^{(1)}$			200	$\mu\text{A}$
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 25\text{ V}$			$\pm 5$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	3.25	4.00	4.75	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$ , $I_D = 10\text{ A}$		102	115	m $\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	-	2000	-	pF
$C_{oss}$	Output capacitance		-	130	-	pF
$C_{rSS}$	Reverse transfer capacitance		-	1.5	-	pF
$C_{oss\text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0\text{ to }520\text{ V}$ , $V_{GS} = 0\text{ V}$	-	339	-	pF
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz}$ , open drain	-	1.6	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 520\text{ V}$ , $I_D = 28\text{ A}$ , $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 14. Test circuit for gate charge behavior)	-	46	-	nC
$Q_{gs}$	Gate-source charge		-	13.5	-	nC
$Q_{gd}$	Gate-drain charge		-	20	-	nC

1.  $C_{oss\text{ eq.}}$  is defined as the constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 325\text{ V}$ , $I_D = 14\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$	-	17	-	ns
$t_r$	Rise time		-	3.3	-	ns
$t_{d(off)}$	Turn-off delay time	(see Figure 13. Switching times test circuit for resistive load and Figure 18. Switching time waveform)	-	46	-	ns
$t_f$	Fall time		-	8	-	ns

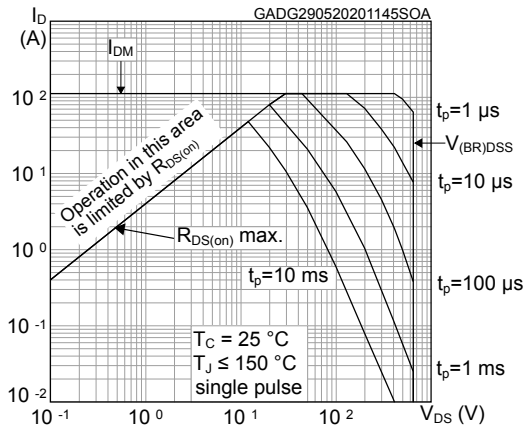
**Table 7. Source-drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		28	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		112	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 28\text{ A}, V_{GS} = 0\text{ V}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 28\text{ A}, di/dt = 100\text{ A}/\mu\text{s},$	-	126		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60\text{ V}$	-	0.63		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	10		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 28\text{ A}, di/dt = 100\text{ A}/\mu\text{s},$	-	220		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60\text{ V}, T_J = 150\text{ }^\circ\text{C}$	-	2.1		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	19		A

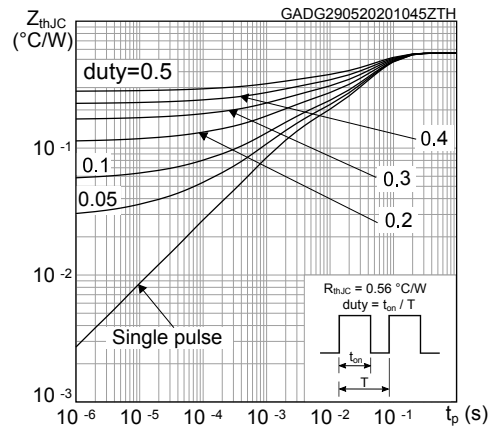
1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

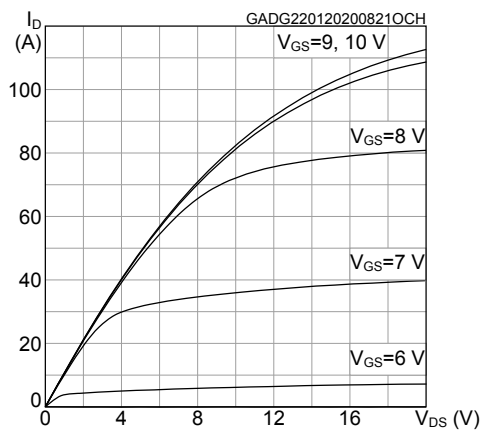
**Figure 1. Safe operating area**



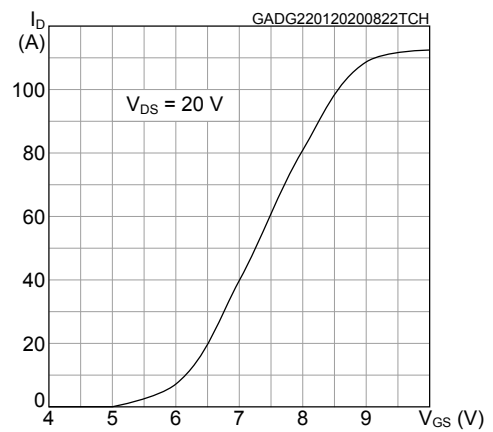
**Figure 2. Maximum transient thermal impedance**



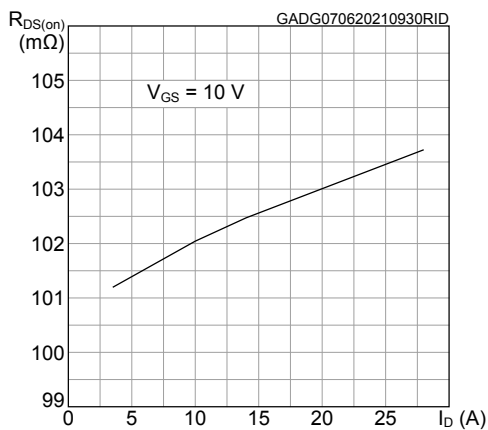
**Figure 3. Typical output characteristics**



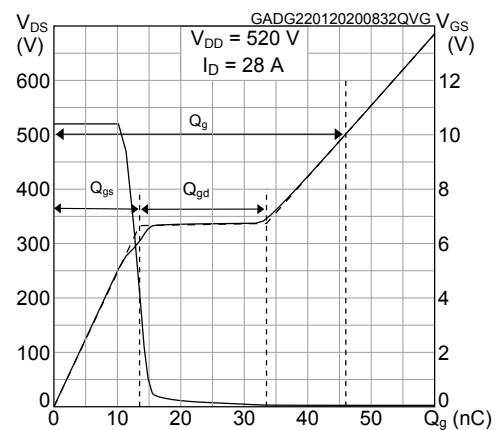
**Figure 4. Typical transfer characteristics**



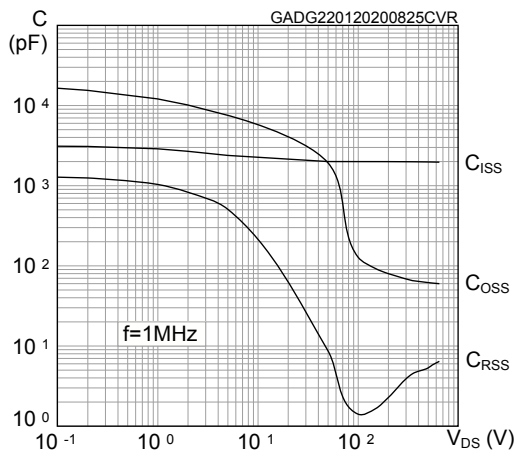
**Figure 5. Typical drain-source on-resistance**



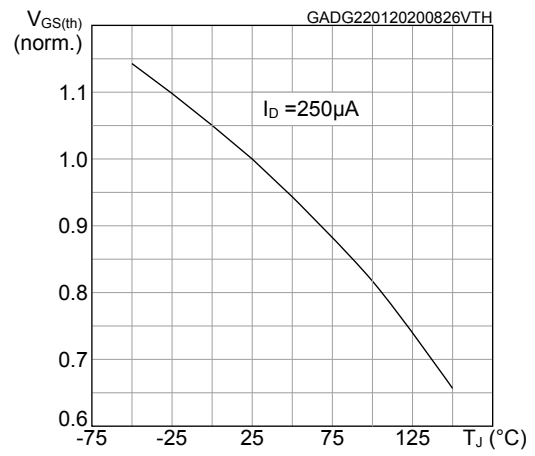
**Figure 6. Typical gate charge characteristics**



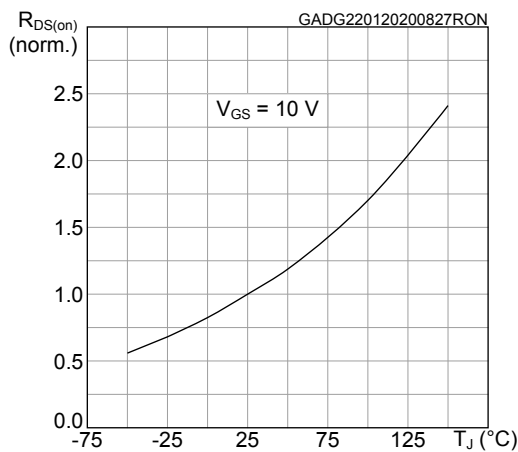
**Figure 7. Typical capacitance characteristics**



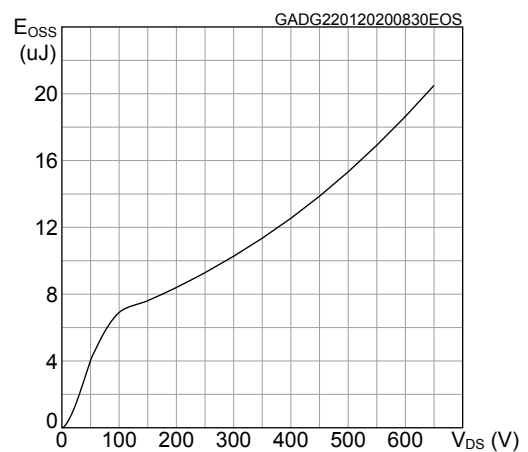
**Figure 8. Normalized gate threshold vs temperature**



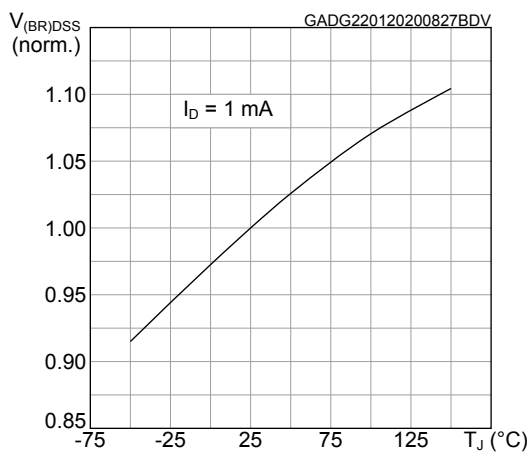
**Figure 9. Normalized on-resistance vs temperature**



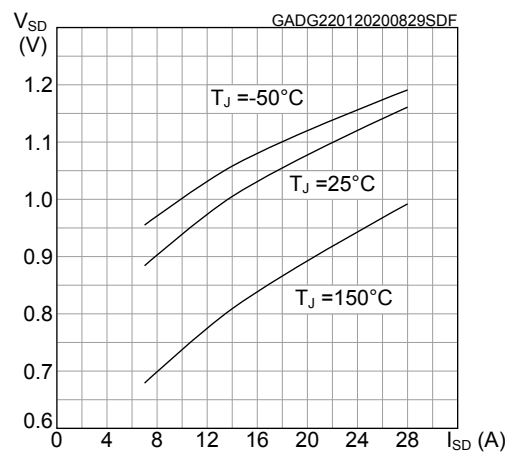
**Figure 10. Typical output capacitance stored energy**



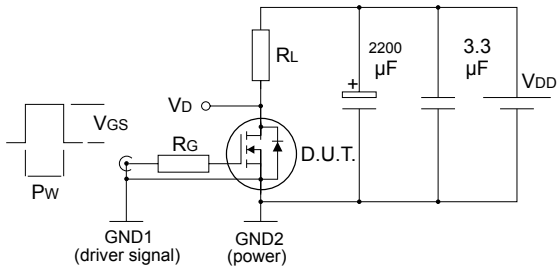
**Figure 11. Normalized breakdown voltage vs temperature**



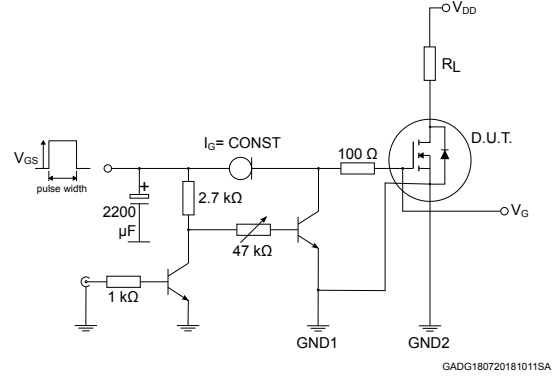
**Figure 12. Typical reverse diode forward characteristics**



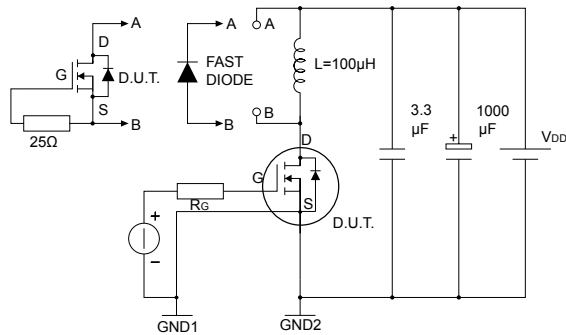
### 3 Test circuits

**Figure 13. Switching times test circuit for resistive load**


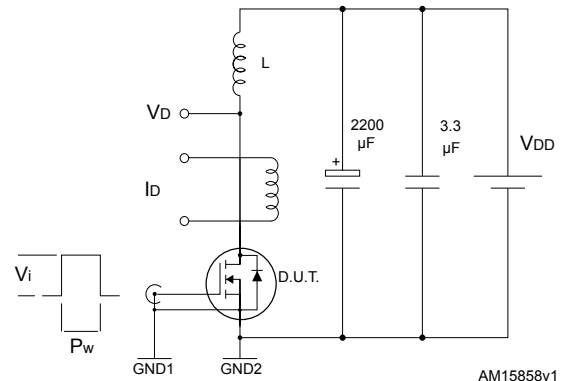
AM15855v1

**Figure 14. Test circuit for gate charge behavior**


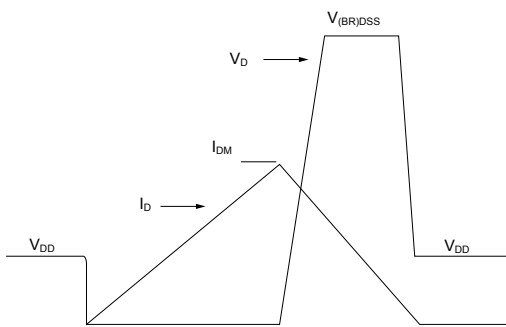
GADG180720181011SA

**Figure 15. Test circuit for inductive load switching and diode recovery times**


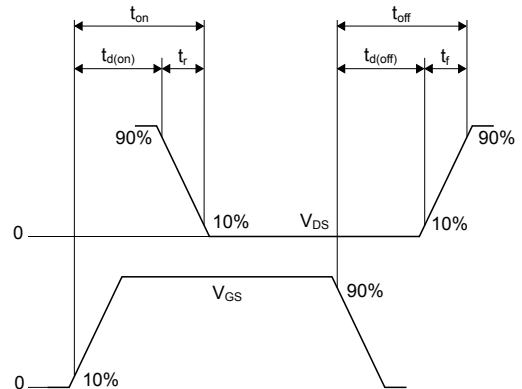
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**Figure 16. Unclamped inductive load test circuit**


AM15858v1

**Figure 17. Unclamped inductive waveform**


AM01472v1

**Figure 18. Switching time waveform**


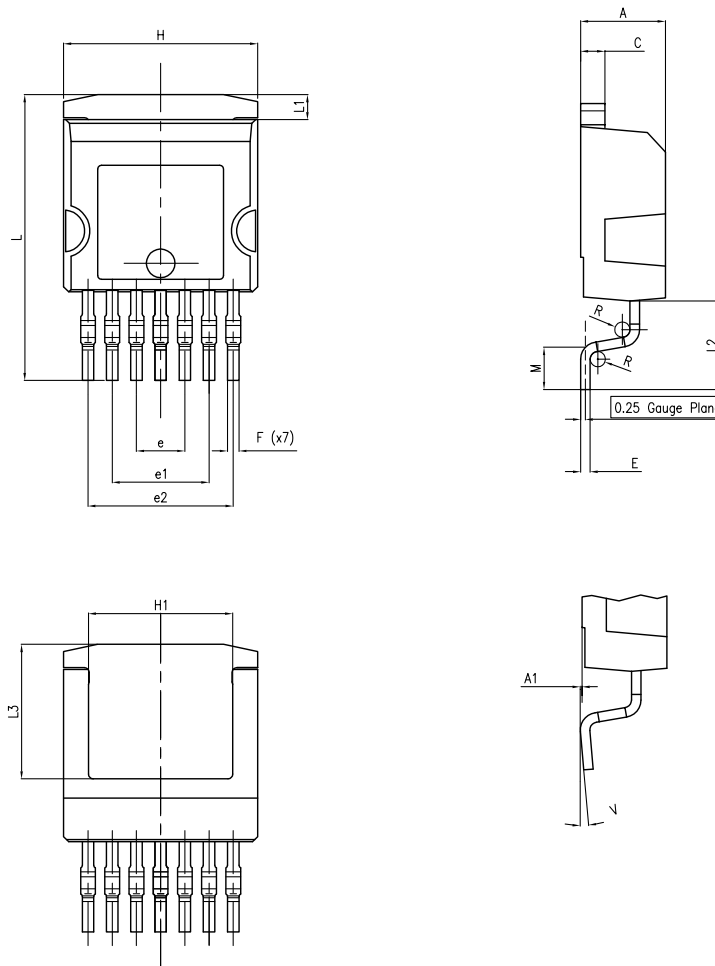
AM01473v1

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 H<sup>2</sup>PAK-7 package information

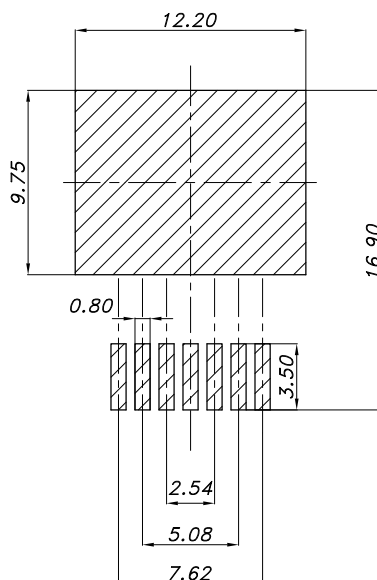
Figure 19. H<sup>2</sup>PAK-7 package outline



**Table 8. H<sup>2</sup>PAK-7 package mechanical data**

Dim.	mm	
	Min.	Max.
A	4.30	4.80
A1	0.03	0.20
C	1.17	1.37
e	2.34	2.74
e1	4.88	5.28
e2	7.42	7.82
E	0.45	0.60
F	0.50	0.70
H	10.00	10.40
H1	7.40	7.60
L	14.75	15.25
L1	1.27	1.40
L2	4.35	4.95
L3	6.85	7.25
M	1.90	2.50
R	0.20	0.60
V	0°	8°

**Figure 20. H<sup>2</sup>PAK-7 recommended footprint**

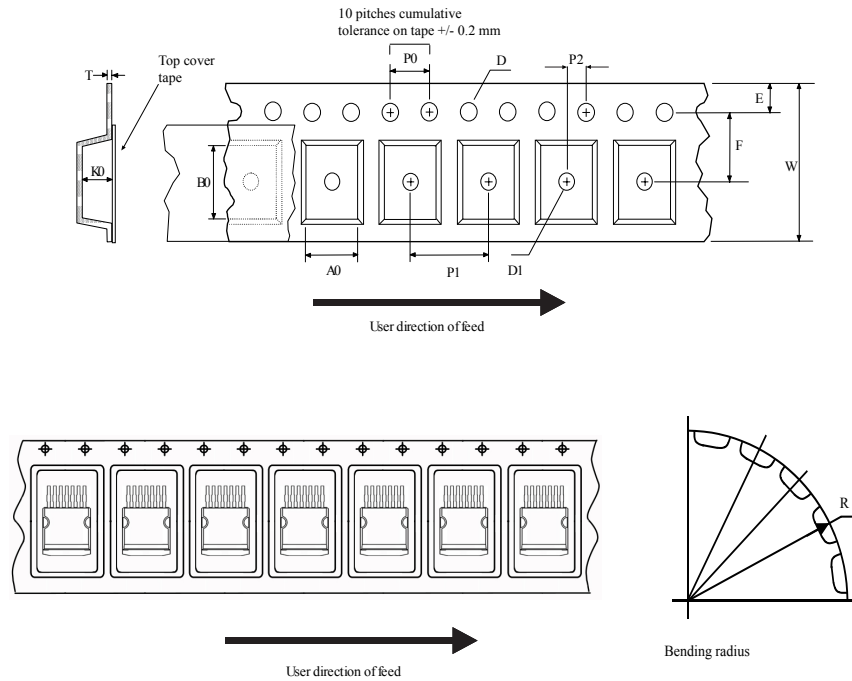


footprint\_DM00249216\_4

*Note: Dimensions are in mm.*

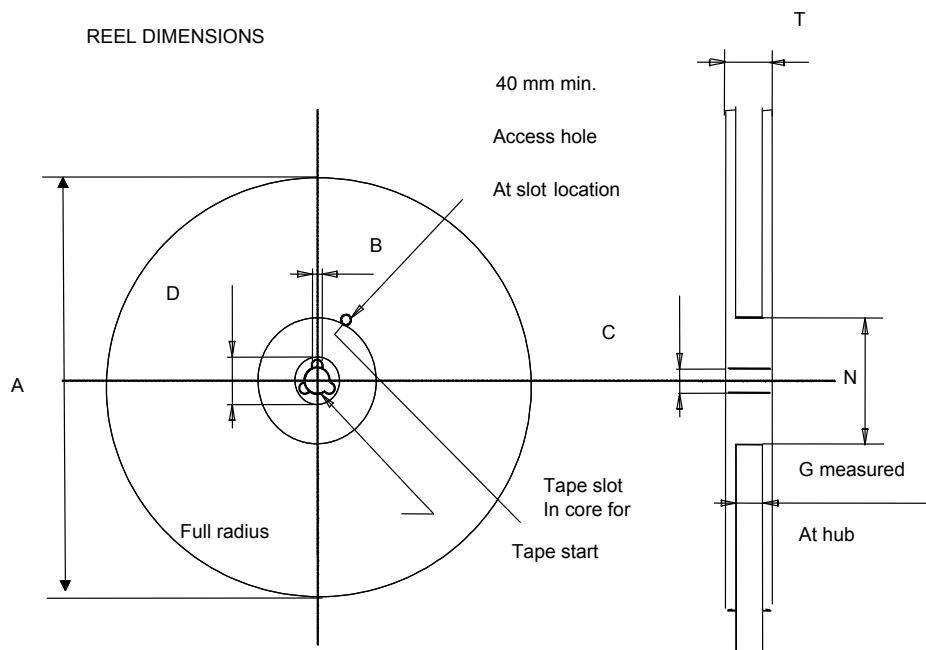
## 4.2 Packing information

Figure 21. Tape outline



GADG160620211017SA

Figure 22. Reel outline



**Table 9. Tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

## Revision history

**Table 10. Document revision history**

Date	Revision	Changes
01-Feb-2021	1	First release.
24-Jun-2021	2	Modified $R_{DS(on)max}$ . on cover page. Modified Table 1. Absolute maximum ratings, Table 2. Thermal data, Table 4. On/off-state and Table 7. Source-drain diode. Updated Section 3 Test circuits. Modified Figure 21. Tape outline. Minor text changes.

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